

SPP2095

The SPP2095 is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application, such as DC/DC converter and Desktop computer power management.

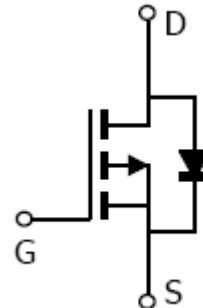
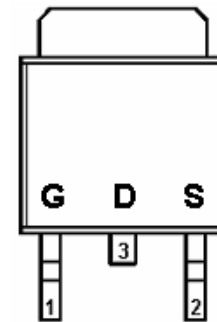
The package is universally preferred for commercial industrial surface mount applications

- Power Management in Desktop Computer
- DC/DC Converter
- LCD Display inverter

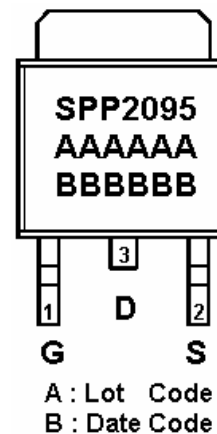
FEATURES

- ◆ -20V/-6.0A, $R_{DS(ON)} = 65m\Omega @ V_{GS} = -4.5V$
- ◆ -20V/-3.6A, $R_{DS(ON)} = 850m\Omega @ V_{GS} = -2.5V$
- ◆ -20V/-2.0A, $R_{DS(ON)} = 105m\Omega @ V_{GS} = -1.8V$
- ◆ Super high density cell design for extremely low RDS (ON)
- ◆ Exceptional on-resistance and maximum DC current capability
- ◆ TO-252-2L package design

PIN CONFIGURATION (TO-252-2L)



PART MARKING



SPP2095

PIN DESCRIPTION

Pin	Symbol	Description
1	G	Gate
2	S	Source
3	D	Drain

ORDERING INFORMATION

Part Number	Package	Part Marking
SPP2095T252RG	TO-252-2L	SPP2095

※ Week Code : A ~ Z (1 ~ 26) ; a ~ z (27 ~ 52)

※ SPP2095T252RG : Tape Reel ; Pb – Free

ABSOLUTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	-20	V
Gate –Source Voltage	V _{GSS}	±12	V
Continuous Drain Current(T _J =150°C)	I _D	TA=25°C	-12
		TA=70°C	-8
Pulsed Drain Current	I _{DM}	-20	A
Continuous Source Current(Diode Conduction)	I _S	-12	A
Power Dissipation	P _D	TA=25°C	40
		TA=70°C	20
Operating Junction Temperature	T _J	-55/150	°C
Storage Temperature Range	T _{STG}	-55/150	°C
Thermal Resistance-Junction to Ambient	R _{θJA}	105	°C/W

ELECTRICAL CHARACTERISTICS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-20			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.32		-0.8	
Gate Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 12V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-20V, V_{GS}=0V$			-1	uA
		$V_{DS}=-20V, V_{GS}=0V$ $T_J=55^\circ C$			-5	
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-4.5V, I_D=-6.0A$		0.055	0.065	Ω
		$V_{GS}=-2.5V, I_D=-3.6A$		0.072	0.085	
		$V_{GS}=-1.8V, I_D=-2.0A$		0.092	0.105	
Forward Transconductance	g_{fs}	$V_{DS}=-5V, I_D=-2.8A$		6		S
Diode Forward Voltage	V_{SD}	$I_S=-6A, V_{GS}=0V$		-0.8	-1.2	V
Dynamic						
Total Gate Charge	Q_g	$V_{DS}=-10V, V_{GS}=-4.5V$ $I_D=-8.0A$		4.8	8	nC
Gate-Source Charge	Q_{gs}			1.0		
Gate-Drain Charge	Q_{gd}			1.0		
Input Capacitance	C_{iss}	$V_{DS}=-10V, V_{GS}=0V$ $f=1MHz$		485		pF
Output Capacitance	C_{oss}			85		
Reverse Transfer Capacitance	C_{rss}			40		
Turn-On Time	$t_{d(on)}$	$V_{DD}=-10V, R_L=6\Omega$ $I_D=-1.0A, V_{GEN}=-4.5V$ $R_G=6\Omega$		10	16	ns
	t_r			13	23	
Turn-Off Time	$t_{d(off)}$			18	25	
	t_f			15	20	